

09/852,824

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L2	151	solder adj via <i>zb</i>	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:26
2	BRS	L3	432	flip adj chip adj assembly	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:26
3	BRS	L4	80	reflowable adj material	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:26
4	BRS	L5	3994	reflowing	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:26
5	BRS	L6	28317	electroplating	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:26
6	BRS	L9	106	3 and 6	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:27
7	BRS	L1	8	bumpless adj flip adj chip adj assembly — 4350,633 DP- 6319,751	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:31
8	BRS	L8	5	2 and 3	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:33

	Type	L #	Hits	Search Text	DBs	Time Stamp
9	BRS	L10	5	3 and 4 and 6	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:34
10	BRS	L7	36	4 and 5	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:37
11	BRS	L11	9451	soi <i>89/906,823</i>	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:37
12	BRS	L12	1054	soi adj wafer	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:38
13	BRS	L13	318	soi adj wafer and oxide adj film	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:38
14	BRS	L14	15	soi adj wafer and oxide adj film and ion adj implanted adj layer <i>DP-6,284,629</i>	USPAT; US-PGP UB; EPO; JPO	2002/05/07 18:39

-6,251,754

-6,221,738

ME-6,143,628

-5,854,123